

09/816,055

L Number	Hits	Search Text	DB	Time stamp
1	837	((ball adj grid adj array) or bga) and @ad<20000324 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:35
2	43	((ball adj grid adj array) or bga) and @ad<20000324 and wafer) and (multilayer near4 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:35
3	1561	((438/107) or (257/724)).CCLS.) and @ad<20000324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:57
4	981	((438/107) or (257/724)).CCLS.) and @ad<20000324) and (integrat\$ or interconnect\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:58
5	317	((438/107) or (257/724)).CCLS.) and @ad<20000324) and (integrat\$ or interconnect\$) and (substrate near4 layers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:59
-	1838	((438/107) or (257/724)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:33
-	1561	((438/107) or (257/724)).CCLS.) and @ad<20000324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/08 11:50
-	199	((438/107) or (257/724)).CCLS.) and @ad<20000324) and (mcm or (multi adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/05 21:03
-	2921	(mcm or (multi adj chip)) and @ad<20000324 and mount\$ and integrate\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/05 21:07
-	1619	((mcm or (multi adj chip)) and @ad<20000324 and mount\$ and integrate\$) and plurality and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/05 21:08
-	102	((mcm or (multi adj chip)) and @ad<20000324 and mount\$ and integrate\$) and plurality and semiconductor) and (esd or electrostatic) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/05 21:09